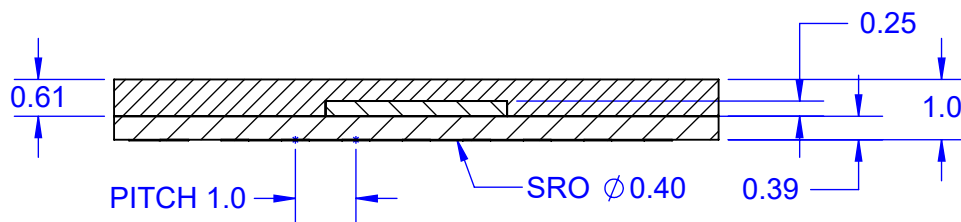
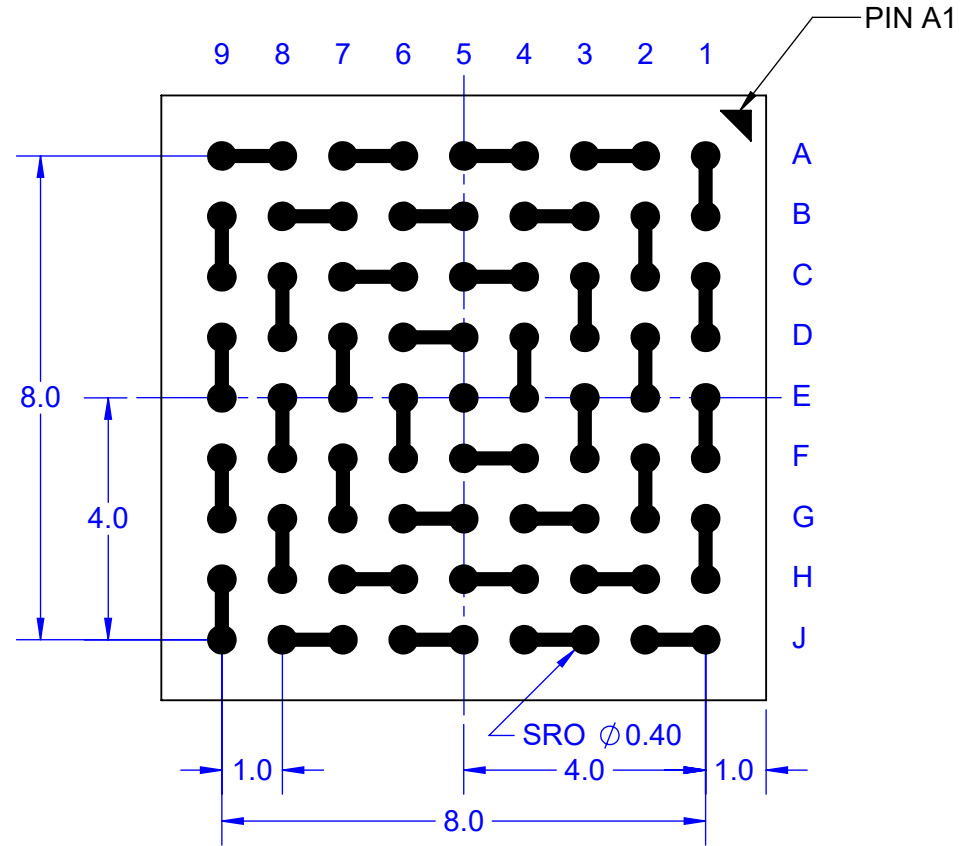
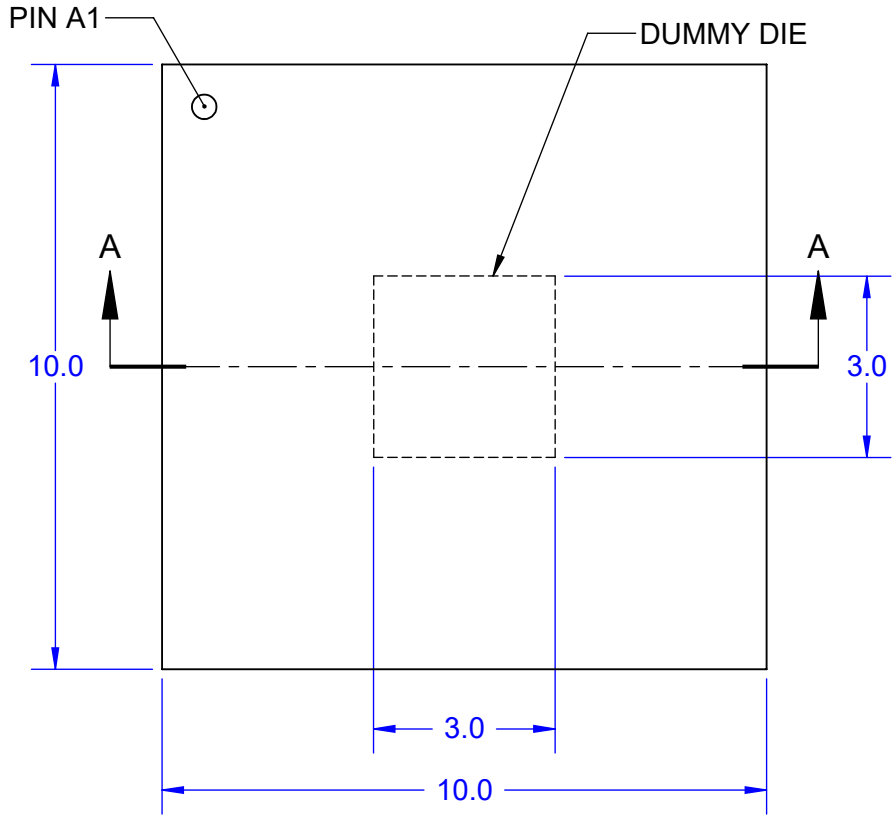


TOP VIEW



SECTION A-A

Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): NONE.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.40mm [16 MIL].
- 5) PAD Cu DIAMETER: 0.508mm [20 MIL].
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE: OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LGA81T1.0G-DC099D	NONE	YES	YES	YES

TopLine[®]

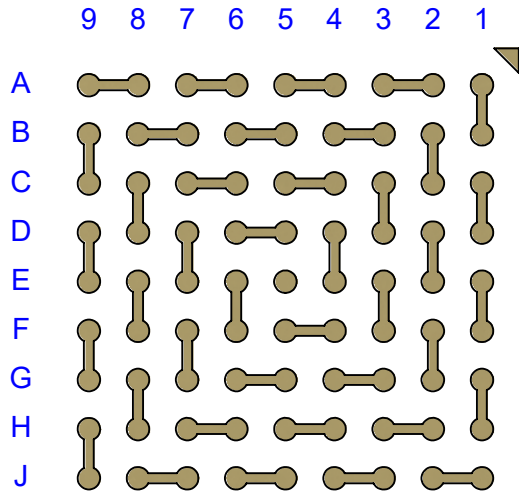
TITLE LGA81T1.0G-DC099D
DAISY CHAIN DUMMY

SCALE 7:1	SIZE A	DRAWING NO. 510990	REV B
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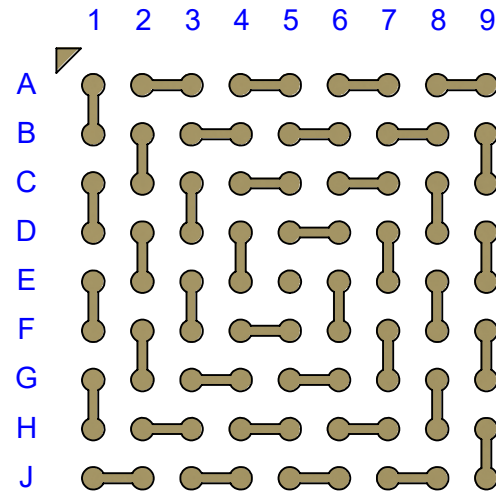
DO NOT SCALE DRAWING

SHEET 1 OF 4

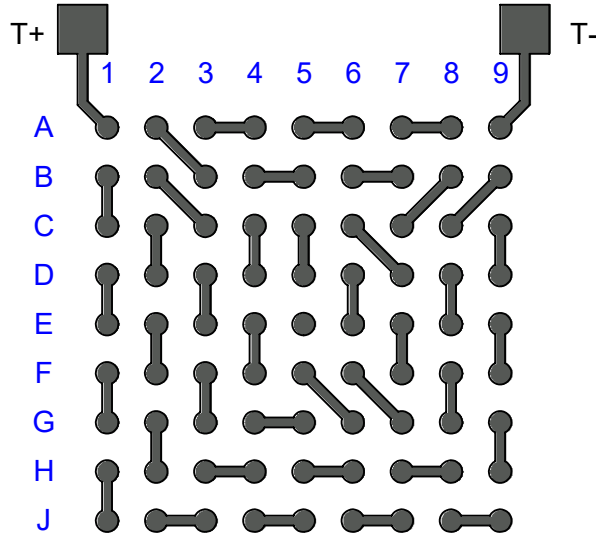
BALL VIEW



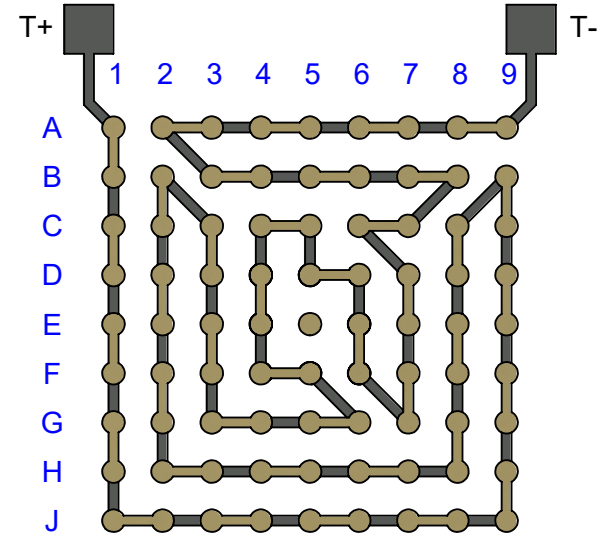
**BOTTOM SIDE
(TOP X-RAY VIEW)**



PCB



**AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)**



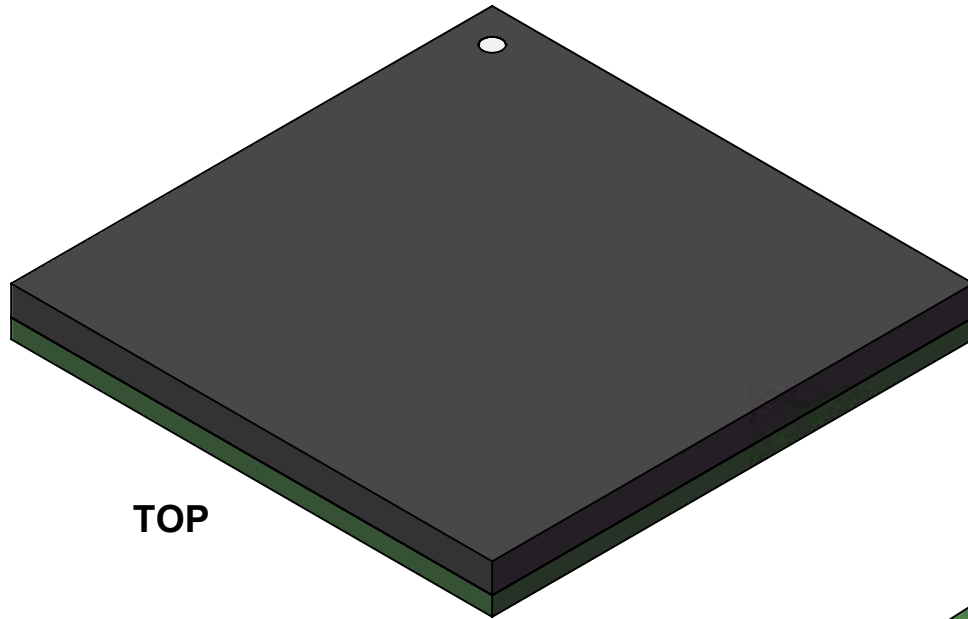
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm [20 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.203mm [8 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.40mm [16 MIL].

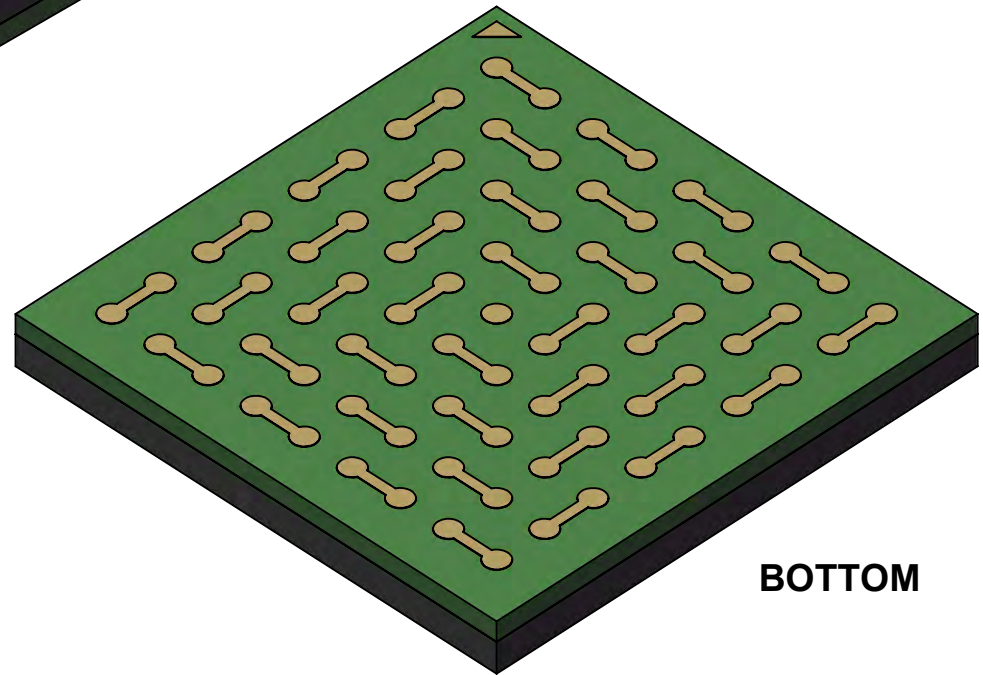
TopLine[®]

TITLE			
LGA81T1.0G-DC099D DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
6.5:1	A	510990	B
DO NOT SCALE DRAWING			SHEET 2 OF 4

**MODEL
WITHOUT SOLDER BALL**



TOP



BOTTOM

TopLine®

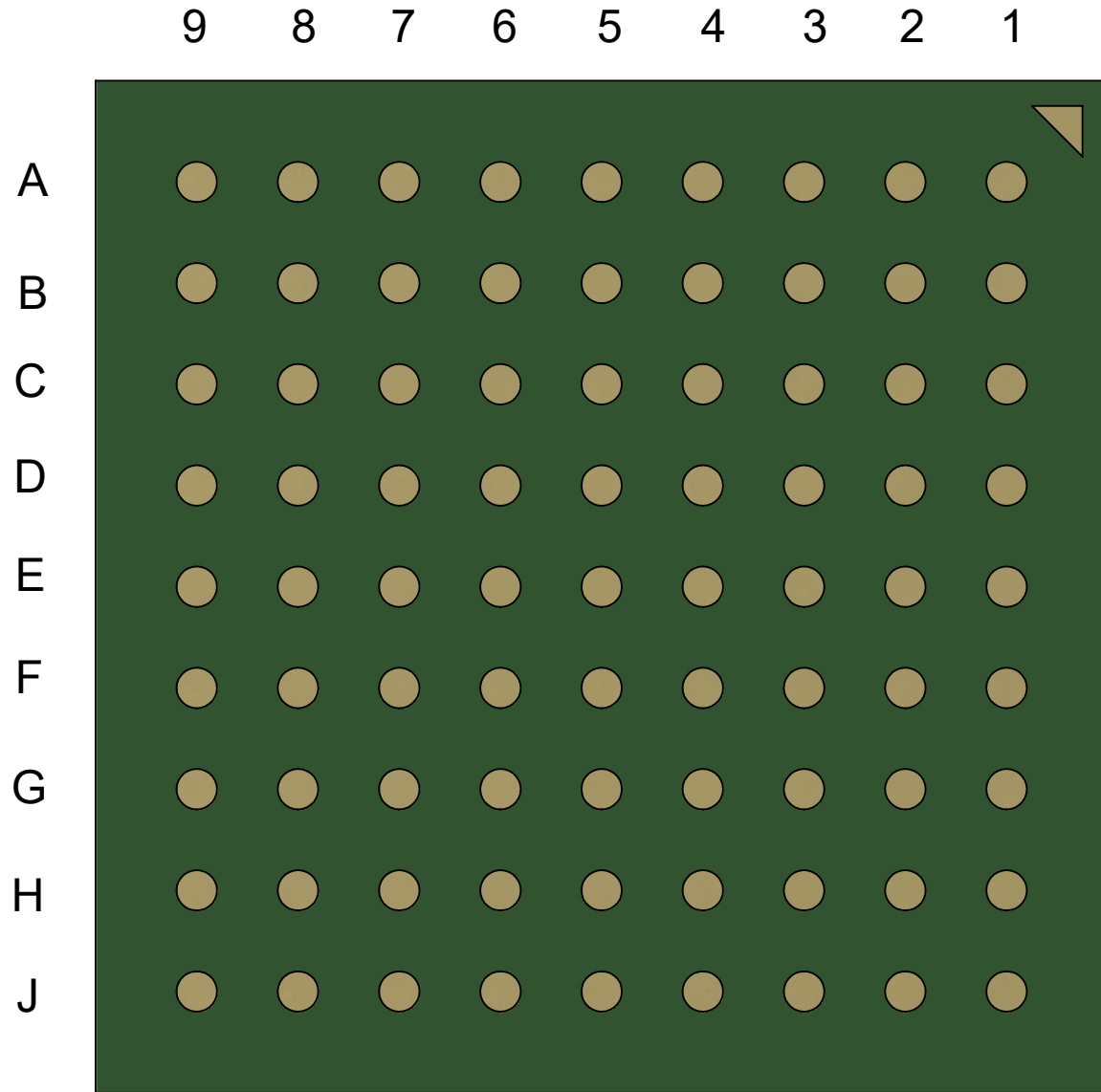
TITLE LGA81T1.0G-DC099D
DAISY CHAIN DUMMY

SCALE 9:1	SIZE A	DRAWING NO. 510990	REV B
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DO NOT SCALE DRAWING

SHEET 3 OF 4

**BOTTOM SOLDER MASK
(RIGHT READING)**



TopLine®			
TITLE		LGA81T1.0C-DC099D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
9:1	A	510990	B
DO NOT SCALE DRAWING			SHEET 4 OF 4